

**PART INFORMATION**

Mfg Item Number	MPC755CRX400TE
Mfg Item Name	FCCBGA 360 25SQ*3.2P1.27

**SUPPLIER**

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-06-06
Response Document ID	8417K00092D031A1.31
Contact Name	Freescale Semiconductor Inc
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

**DECLARATION**

EU RoHS	No
Pb Free	No
HalogenFree	Yes
Plating Indicator	e0
EU RoHS Exemption(s)	15

**MANUFACTURING**

Mfg Item Number	MPC755CRX400TE
Mfg Item Name	FCCBGA 360 25SQ*3.2P1.27
Version	ALL
Weight	4.708700
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	1
Peak Processing Temperature	220 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
	15:Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Underfill	0.0308						g				
Underfill		Solvents, additives, and other materials	Methylhexahydrophthalic anhydride	25550-51-0		0.0046528	g	151065	15.1065	988	0.0988
Underfill		Plastics/polymers	1,3-bis(2,3-epoxypropoxy)-2,2-dimethylpropane	17557-23-2		0.00171541	g	55695	5.5695	364	0.0364
Underfill		Plastics/polymers	1,6-Bis(2,3-epoxypropoxy) naphthalene	27610-48-6		0.00171541	g	55695	5.5695	364	0.0364
Underfill		Plastics/polymers	Elastomer Modified Diglycidyl Ether	68809-14-6		0.00171541	g	55695	5.5695	364	0.0364
Underfill		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.02010564	g	652781	65.2781	4269	0.4269
Underfill		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.00089533	g	29069	2.9069	190	0.019
Ceramic Substrate	2.9082						g				
Ceramic Substrate		Metals	Aluminum Oxides (Al2O3)	1344-28-1		2.50364612	g	860892	86.0892	531720	53.172
Ceramic Substrate		Metals	Chromium, metal	7440-47-3		0.04132843	g	14211	1.4211	8777	0.8777
Ceramic Substrate		Metals	Gold, metal	7440-57-5		0.00023556	g	81	0.0081	50	0.005
Ceramic Substrate		Lead/Lead Compounds	Lead	7439-92-1		0.00000582	g	2	0.0002	1	0.0001
Ceramic Substrate		Metals	Molybdenum, metal	7439-98-7		0.02476041	g	8514	0.8514	5258	0.5258
Ceramic Substrate		Nickel (external applications only)	Nickel	7440-02-0		0.0090794	g	3122	0.3122	1928	0.1928
Ceramic Substrate		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.21215028	g	72949	7.2949	45054	4.5054
Ceramic Substrate		Metals	Tungsten, metal	7440-33-7		0.11699398	g	40229	4.0229	24846	2.4846
Capacitor_0201	0.0816						g				
Capacitor_0201		Metals	Copper, metal	7440-50-8		0.005712	g	70000	7	1213	0.1213
Capacitor_0201		Nickel (external applications only)	Nickel	7440-02-0		0.0172992	g	212000	21.2	3673	0.3673
Capacitor_0201		Metals	Tin, metal	7440-31-5		0.0004896	g	6000	0.6	103	0.0103
Capacitor_0201		Metals	Barium titanate	12047-27-7		0.0580992	g	712000	71.2	12338	1.2338
Solder Balls - High Lead	1.44						g				
Solder Balls - High Lead		Lead/Lead Compounds	Lead	7439-92-1		1.2888	g	895000	89.5	273706	27.3706
Solder Balls - High Lead		Metals	Tin, metal	7440-31-5		0.1512	g	105000	10.5	32110	3.211
Solder Paste	0.1247						g				
Solder Paste		Lead/Lead Compounds	Lead	7439-92-1		0.046139	g	370000	37	9798	0.9798
Solder Paste		Metals	Tin, metal	7440-31-5		0.078561	g	630000	63	16684	1.6684
High Pb Bumped Semiconductor D	0.0943				15		g				
High Pb Bumped Semiconductor D		Lead/Lead Compounds	Lead	7439-92-1		0.00888089	g	94177	9.4177	1886	0.1886
High Pb Bumped Semiconductor D		Nickel (external applications only)	Nickel	7440-02-0		0.0000778	g	825	0.0825	16	0.0016
High Pb Bumped Semiconductor D		Metals	Tin, metal	7440-31-5		0.00046735	g	4956	0.4956	99	0.0099
High Pb Bumped Semiconductor D		Metals	Titanium, metal	7440-32-6		0.00000396	g	42	0.0042	0	0
High Pb Bumped Semiconductor D		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.0008487	g	9000	0.9	180	0.018
High Pb Bumped Semiconductor D		Glass	Silicon, doped	-		0.0840213	g	891000	89.1	17843	1.7843
Capacitor Solder Paste	0.0291						g				
Capacitor Solder Paste		Metals	Copper, metal	7440-50-8		0.001455	g	5000	0.5	30	0.003
Capacitor Solder Paste		Lead/Lead Compounds	Lead	7439-92-1		0.0000242	g	83	0.0083	0	0
Capacitor Solder Paste		Metals	Silver, metal	7440-22-4		0.000873	g	30000	3	185	0.0185
Capacitor Solder Paste		Metals	Tin, metal	7440-31-5		0.02807908	g	964917	96.4917	5963	0.5963

## LINKS

MCD LINK	
NXP website	<a href="http://www.nxp.com">http://www.nxp.com</a>
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf</a>
China RoHS	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY</a>
REACH signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf</a>
ELV signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf</a>
Conflict Minerals statement	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf</a>
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX</a>
FAQ	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ</a>
Technical Service Request	<a href="http://www.nxp.com/support/sales-and-support:SUPPORTHOME">http://www.nxp.com/support/sales-and-support:SUPPORTHOME</a>
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	<a href="http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf">http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf</a>

IPC1752 XML LINKS

[http://www.freescale.com/mcdfs/MPC755CRX400TE\\_IPC1752\\_v11.xml](http://www.freescale.com/mcdfs/MPC755CRX400TE_IPC1752_v11.xml)

[http://www.freescale.com/mcdfs/MPC755CRX400TE\\_IPC1752A.xml](http://www.freescale.com/mcdfs/MPC755CRX400TE_IPC1752A.xml)